# 2SA844

### Silicon PNP Epitaxial

# **HITACHI**

ADE-208-320 (Z) 1st. Edition Mar. 2001

### Application

Low frequency amplifier

#### Outline

TO-92 (1)

1. Emitter
2. Collector
3. Base



### 2SA844

### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit	
Collector to base voltage	$V_{\text{CBO}}$	<b>–</b> 55	V	
Collector to emitter voltage	V <sub>CEO</sub>	<b>–</b> 55	V	
Emitter to base voltage	$V_{EBO}$	<b>–</b> 5	V	
Collector current	I <sub>c</sub>	-100	mA	
Emitter current	I <sub>E</sub>	100	mA	
Collector power dissipation	P <sub>c</sub>	300	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

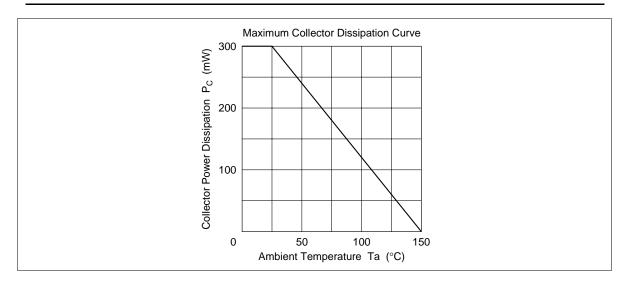
#### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	<b>-</b> 55	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	<b>-</b> 55	_	_	V	$I_{c} = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	<b>-</b> 5	_	_	V	$I_{E} = -10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-100	nA	$V_{CB} = -18 \text{ V}, I_{E} = 0$
Emitter cutoff current	I <sub>EBO</sub>	_	_	<b>-</b> 50	nA	$V_{EB} = -2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h <sub>FE</sub> *1	160	_	800		$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Collector to emitter saturation voltage	$V_{CE(sat)}$	_	-0.1	-0.5	V	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -1 \text{ mA}$
Base to emitter voltage	$V_{\text{BE}}$	_	-0.66	-0.75	V	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Gain bandwidth product	f <sub>T</sub>	_	200	_	MHz	$V_{CE} = -12 \text{ V}, I_{E} = -2 \text{ mA}$
Collector output capacitance	Cob	_	2.0	_	pF	$V_{CB} = -10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

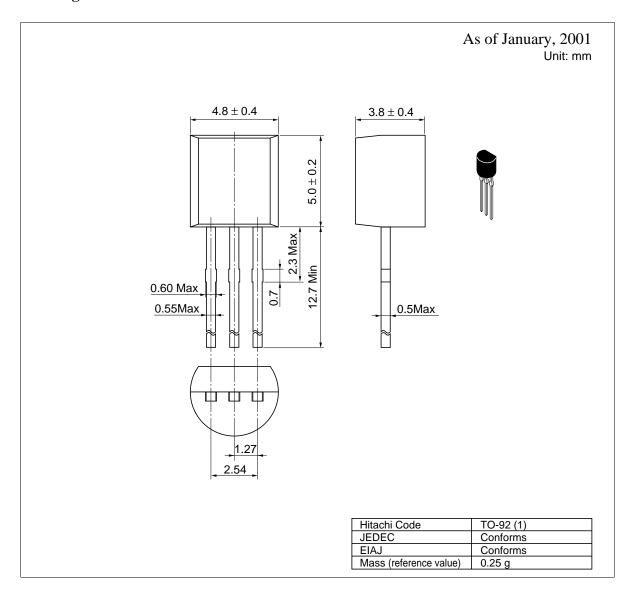
Note: 1. The 2SA844 is grouped by  $h_{\text{FE}}$  as follows.

С	D	E
160 to 320	250 to 500	400 to 800

See characteristic curves of 2SA836.



#### **Package Dimensions**



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